

L Number	Hits	Search Text	DB	Time stamp
1	4634	(250/306,307,309,311).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:20
2	19716	(inspect\$5 near4 (hole or semiconductor or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:42
3	161	((inspect\$5 near4 (hole or semiconductor or wafer))) and (detect\$4 with current) and ((charged adj particle) and electron)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:43
4	45	((inspect\$5 near4 (hole or semiconductor or wafer))) and (detect\$4 with current) and ((charged adj particle) and electron)) and ground	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:26
5	37	((inspect\$5 near4 (hole or semiconductor or wafer))) and (detect\$4 with current) and ((charged adj particle) and electron)) and ground) and display\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:43
6	7	((inspect\$5 near4 (hole or semiconductor or wafer))) and (detect\$4 with current) and ((charged adj particle) and electron)) and ground) and display\$3) and map	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:43
7	8	((inspect\$5 near4 (hole or semiconductor or wafer))) and (detect\$4 with current) and ((charged adj particle) and electron)) and ground) and display\$3) and map\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:37
8	32	((inspect\$5 near4 (hole or semiconductor or wafer))) and (detect\$4 with current) and ((charged adj particle) and electron)) and ground) and display\$3) and region	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:44
9	32	((inspect\$5 near4 (hole or semiconductor or wafer))) and (detect\$4 with current) and ((charged adj particle) and electron)) and ground) and display\$3) and region) and region	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:37
10	8	((inspect\$5 near4 (hole or semiconductor or wafer))) and (detect\$4 with current) and ((charged adj particle) and electron)) and ground) and display\$3) and region) and map\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:38
11	17	((inspect\$5 near4 (hole or semiconductor or wafer))) and (detect\$4 with current) and ((charged adj particle) and electron)) and ground) and display\$3) and region) and (detect\$5 with current with (wafer or sample or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:39
12	2	((inspect\$5 near4 (hole or semiconductor or wafer))) and (detect\$4 with current) and ((charged adj particle) and electron)) and ground) and display\$3) and region) and (detect\$5 with current with (wafer or sample or substrate) with ground\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:40
13	4	((250/306,307,309,311).CCLS.) and (detect\$5 with current with (wafer or sample or substrate) with ground\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:40

14	2	((((250/306,307,309,311).CCLS.) and (detect\$5 with current with (wafer or sample or substrate) with ground\$3)) and (inspect\$5 near4 (hole or semiconductor or wafer)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:42
15	1	((((250/306,307,309,311).CCLS.) and (detect\$5 with current with (wafer or sample or substrate) with ground\$3)) and (inspect\$5 near4 (hole or semiconductor or wafer))) and (detect\$4 with current) and ((charged adj particle) and electron)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:43
17	1	(((((250/306,307,309,311).CCLS.) and (detect\$5 with current with (wafer or sample or substrate) with ground\$3)) and (inspect\$5 near4 (hole or semiconductor or wafer))) and (detect\$4 with current) and ((charged adj particle) and electron)) and map	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:43
18	1	(((((250/306,307,309,311).CCLS.) and (detect\$5 with current with (wafer or sample or substrate) with ground\$3)) and (inspect\$5 near4 (hole or semiconductor or wafer))) and (detect\$4 with current) and ((charged adj particle) and electron)) and region	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:44
19	1	(((((250/306,307,309,311).CCLS.) and (detect\$5 with current with (wafer or sample or substrate) with ground\$3)) and (inspect\$5 near4 (hole or semiconductor or wafer))) and display\$3) and ((plural\$5 or multiple) with hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:45
16	2	((((250/306,307,309,311).CCLS.) and (detect\$5 with current with (wafer or sample or substrate) with ground\$3)) and (inspect\$5 near4 (hole or semiconductor or wafer))) and display\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/16 20:45